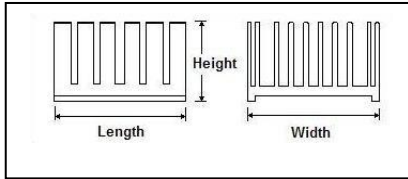
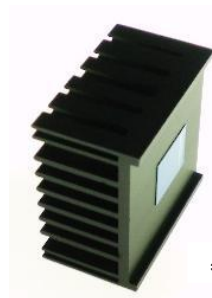




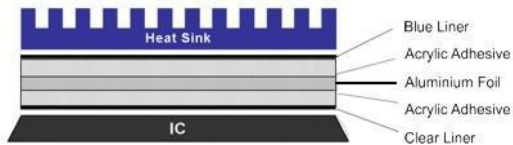
Flip Chip



All ABL's BGA heatsinks are supplied with thermal tape

Model	Width	Length	Height	Pad Size	Anodised Finish	°C/W	°C/W	Wire Form
	[mm]	[mm]	[mm]	[mm]		Natural	Forced 2M/s	
BGA-FC-010	40	40	10.0	20x20	Black	13.50	7.00	WF700/WF300
*BGA-FC-015	40	40	24.0	30x30	Black	11.00	5.50	WF700/WF300

Thermally Conductive Aluminium Foil



All ABL's BGA heatsinks are supplied with thermal tape.

With excellent thermal conductivity, cushioning and gap filling properties, the pad is an ideal thermal interface material specifically designed for heat sink attachment to MPU, chip set and other plastic encapsulated components.

It consists of an aluminium foil backing coated, on both sides, with a very high temperature resistance acrylic adhesive. Due to its high heat performance and adhesive properties this tape can also be use to attach components to a vertical heatsink and to metal enclosure surfaces.

Colour	-	White
Backing Type / Thickness	Mm	Aluminium Foil / 0.10
Adhesive Type / Thickness	Mm	Arylic 0.075 (on clear liner side)
Total Thickness	mm	0,27
Adhesion	Kg/25mm	1,5
Thermal Conductivity	W/m-K	0,95
Thermal Resistance	°C-in ² /W	0,2
Holding Power@23°C	Hour	>72
Holding Power @ 130°C	Hour	>2